LP3879 Micropower 800mA Low Noise "Ceramic Stable" Voltage Regulator for Low Voltage Applications

Check for Samples: LP3879

FEATURES

- **Standard Output Voltage: 1.00V, 1.20V**
- **Custom Voltages Available from 1.0V to 1.2V (50 mV Increments)**
- **Input Voltage: 2.5 to 6V**
- **1% Initial Output Accuracy**
- **Designed for Use with Low ESR Ceramic Capacitors**
- **Very Low Output Noise**
- **Sense Option Improves Load Regulation**
- **8-Lead SO PowerPad and WSON Surface Mount Packages**
- **<10 µA Quiescent Current in Shutdown**
- **Low Ground Pin Current at all Loads**
- **High Peak Current Capability**
- **Over-Temperature/Over-Current Protection**
- **-40°C to +125°C Junction Temperature Range**

APPLICATIONS

- **ASIC Power Supplies In:**
  - **Desktops, Notebooks and Graphic Cards**
  - **Set Top Boxes, Printers and Copiers**
- **DSP and FPGA Power Supplies**
- **SMPS Post-Regulator**
- **Medical Instrumentation**

DESCRIPTION

The LP3879 is a 800 mA fixed-output voltage regulator designed to provide high performance and low noise in applications requiring output voltages between 1.0V and 1.2V.

Using an optimized VIP (Vertically Integrated PNP) process, the LP3879 delivers superior performance:

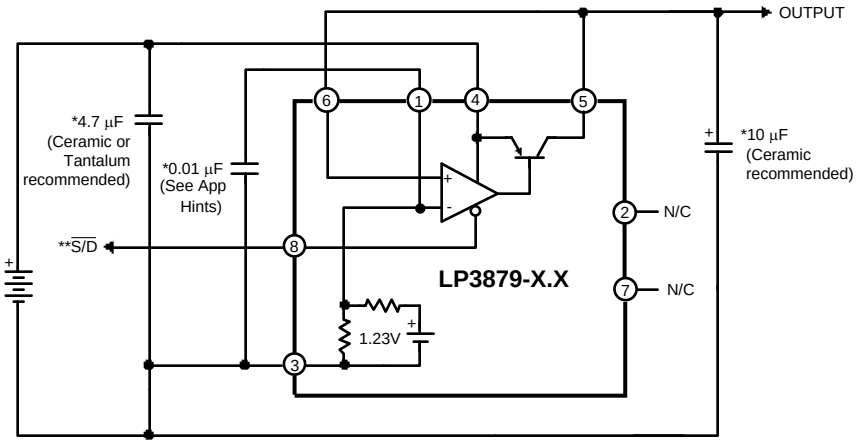
Ground Pin Current: Typically 5.5 mA @ 800 mA load, and 200 µA @ 100 µA load.

Low Power Shutdown: The LP3879 draws less than 10 µA quiescent current when shutdown pin is pulled low.

Precision Output: Ensured output voltage accuracy is 1% at room temperature.

Low Noise: Broadband output noise is only 18 µV (typical) with 10 nF bypass capacitor.

Basic Application Circuit



*Capacitance values shown are minimum required to assure stability. Larger output capacitor provides improved dynamic response. Output capacitor must meet ESR requirements (see Application Information).
**The Shutdown pin must be actively terminated (see Application Information). Tie to INPUT (Pin 4) if not used.

Connection Diagram

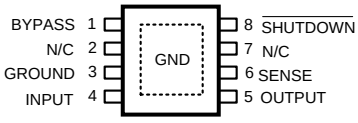


Figure 1. Top View
8-Lead SO PowerPad
See DDA0008B Package

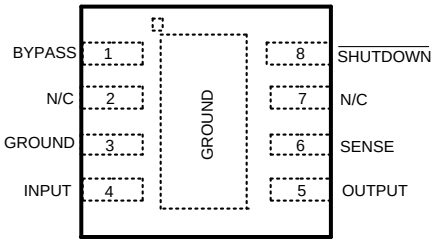


Figure 2. Top View
8-Lead WSON
See NGT0008A Package

PIN DESCRIPTIONS

Pin	Name	Function
1	BYPASS	The capacitor connected between BYPASS and GROUND lowers output noise voltage level and is required for loop stability.
2	N/C	DO NOT CONNECT. This pin is used for post package test and must be left floating.
3	GROUND	Device ground.
4	INPUT	Input source voltage.
5	OUTPUT	Regulated output voltage.
6	SENSE	Remote Sense. Tie directly to output or remotely at point of load for best regulation.
7	N/C	No internal connection.
8	SHUTDOWN	Output is enabled above turn-on threshold voltage. Pull down to turn off regulator output.
SO PowerPad, WSON	SUBSTRATE GROUND	The exposed die attach pad should be connected to a thermal pad at ground potential. For additional information on using Texas Instruments' Non Pull Back WSON package, please refer to WSON application note SNOA401

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings[1][2]

Storage Temperature Range	−65°C to +150°C
Operating Junction Temperature Range	-40°C to +125°C
Lead Temperature (Soldering, 5 seconds)	260°C
ESD Rating[3]	2 kV
Shutdown Pin	1kV
Power Dissipation[4]	Internally Limited
Input Supply Voltage (Survival)	−0.3V to +16V
Input Supply Voltage (Typical Operating)	2.5V to +6V
SENSE Pin	−0.3V to +6V
Output Voltage (Survival)[5]	−0.3V to +6V
I_{OUT} (Survival)	Short Circuit Protected
Input-Output Voltage (Survival)[6]	−0.3V to +16V

(1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
(3) ESD testing was performed using Human Body Model, a 100 pF capacitor discharged through a 1.5 kΩ resistor.
(4) The maximum allowable power dissipation is a function of the maximum junction temperature, $T_J(MAX)$, the junction-to-ambient thermal resistance, θ_{J-A}, and the ambient temperature, T_A. The maximum allowable power dissipation at any ambient temperature is calculated using: $P(MAX) = \frac{T_J(MAX) - T_A}{\theta_{J-A}}$ The value of θ_{J-A} for the WSON and SO PowerPad packages are specifically dependent on PCB trace area, trace material, and the number of layers and thermal vias. If a four layer board is used with maximum vias from the IC center to the heat dissipating copper layers, values of θ_{J-A} which can be obtained are approximately 60°C/W for the SO PowerPad and 40°C/W for the WSON package. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown.
(5) If used in a dual-supply system where the regulator load is returned to a negative supply, the LP3879 output must be diode-clamped to ground.
(6) The output PNP structure contains a diode between the V_{IN} and V_{OUT} terminals that is normally reverse-biased. Forcing the output above the input will turn on this diode and may induce a latch-up mode which can damage the part (see Application Hints).

Electrical Characteristics

Limits in standard typeface are for T_J = 25°C, and limits in **boldface type** apply over the temperature range of -40°C to 125°C. Limits are ensured through design, testing, or correlation. The limits are used to calculate the Average Outgoing Quality Level (AOQL). Unless otherwise specified: V_{IN} = 3.0V, V_{OUT} = 1V, I_L = 1 mA, C_{OUT} = 10 µF, C_{IN} = 4.7 µF, $V_{S/D}$ = 2V, C_{BYPASS} = 10 nF.

Symbol	Parameter	Conditions	Min (1)	Typical (2)	Max (1)	Units
V_O	Output Voltage Tolerance		-1.0	1.00	1.0	$\%V_{nom}$
		1 mA ≤ I_L ≤ 800 mA, 3.0V ≤ V_{IN} ≤ 6V	-2.0 **-3.0**	1.00	2.0 **3.0**	
$\frac{\Delta V_{OUT}}{\Delta V_{IN}}$	Output Voltage Line Regulation	3.0V ≤ V_{IN} ≤ 6V		0.007	0.014 **0.032**	%/V
V_{IN} (min)	Minimum Input Voltage Required To Maintain Output Regulation	I_L = 800 mA, V_{OUT} ≥ $V_{OUT(NOM)}$ - 1%		2.5	**3.1**	V
		I_L = 800 mA, V_{OUT} ≥ $V_{OUT(NOM)}$ - 1% 0 ≤ T_J ≤ 125°C		2.5	**2.8**	
		I_L = 750 mA, V_{OUT} ≥ $V_{OUT(NOM)}$ - 1%		2.5	**3.0**	
I_{GND}	Ground Pin Current	I_L = 100 µA		200	250 **275**	µA
		I_L = 200 mA		1.5	2 **3.3**	mA
		I_L = 800 mA		5.5	8.5 **15**	
I_O(PK)	Peak Output Current	V_{OUT} ≥ $V_{OUT(NOM)}$ − 5%		1200		mA
I_O(MAX)	Short Circuit Current	R_L = 0 (Steady State)		1400		
e_n	Output Noise Voltage (RMS)	BW = 100 Hz to 100 kHz C_{BYPASS} = 10 nF		18		µV(RMS)
$\frac{\Delta V_{OUT}}{\Delta V_{IN}}$	Ripple Rejection	f = 1 kHz		60		dB
SHUTDOWN INPUT						
$V_{S/D}$	S/D Input Voltage	V_H = Output ON		1.4	**1.6**	V
		V_L = Output OFF, I_{IN} ≤ 10 µA	**0.1**	0.50		
		V_{OUT} ≤ 10 mV, I_{IN} ≤ 50 µA		0.6		
$I_{S/D}$	S/D Input Current	$V_{S/D}$ = 0		0.02	**−1**	µA
		$V_{S/D}$ = 5V		5	**15**	

(1) Limits are ensured through testing, statistical correlation, or design.
(2) Typical numbers reperesent the most likely norm for 25°C operation.

Typical Performance Characteristics

Unless otherwise specified: V_{IN} = 3.3V, V_{OUT} = 1V, I_L = 1 mA, C_{IN} = 4.7 µF, C_{OUT} = 10 µF, $V_{S/D}$ = 2V, C_{BYP} = 10 nF, T_J = 25°C.

I_{GND} vs Temperature

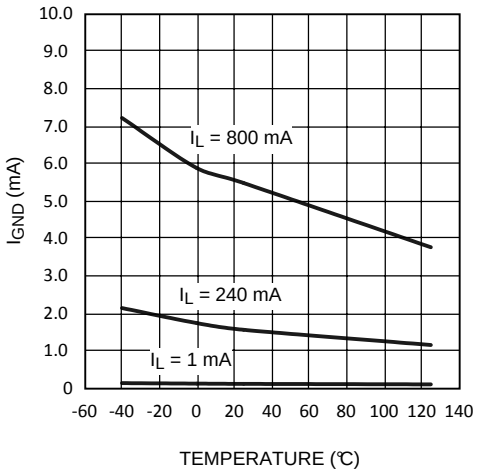


Figure 3.

Minimum V_{IN} Over Temperature

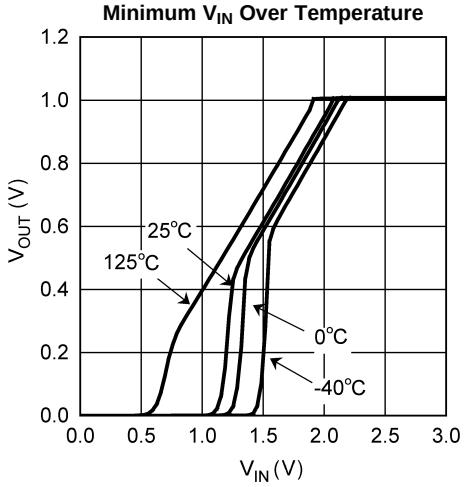


Figure 4.

I_{GND} vs I_{Load}

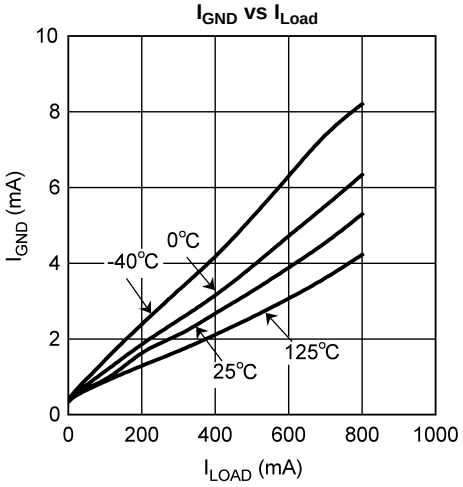


Figure 5.

V_{OUT} vs Temperature

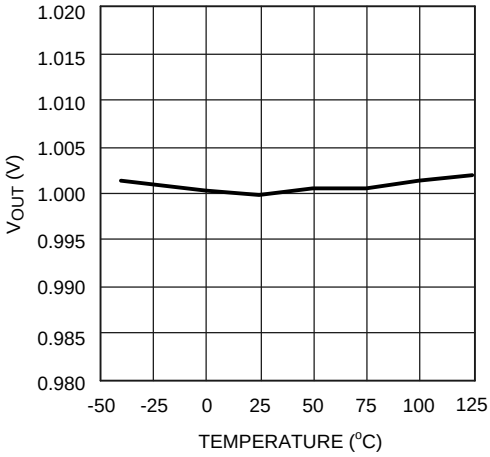


Figure 6.

V_{OUT} vs Temperature

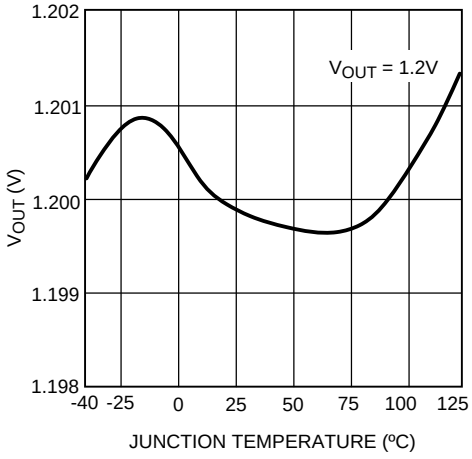


Figure 7.

Ripple Rejection

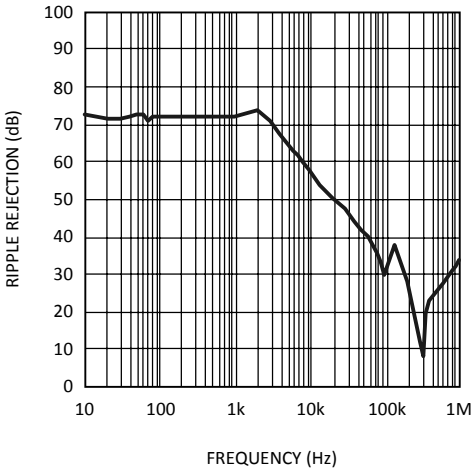


Figure 8.

Typical Performance Characteristics (continued)

Unless otherwise specified: V_{IN} = 3.3V, V_{OUT} = 1V, I_L = 1 mA, C_{IN} = 4.7 µF, C_{OUT} = 10 µF, $V_{S/D}$ = 2V, C_{BYP} = 10 nF, T_J = 25°C.

Ripple Rejection

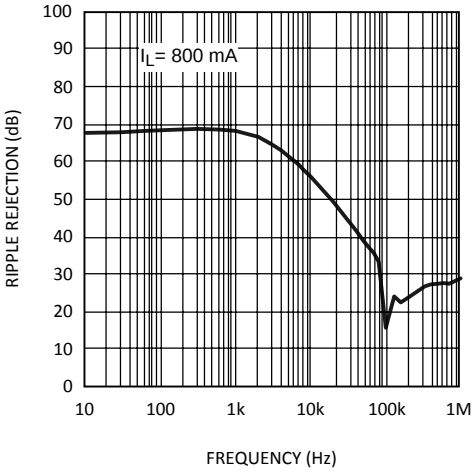


Figure 9.

Line Transient Response

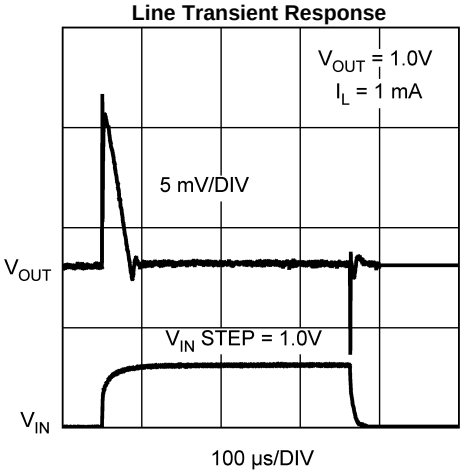


Figure 10.

Line Transient Response

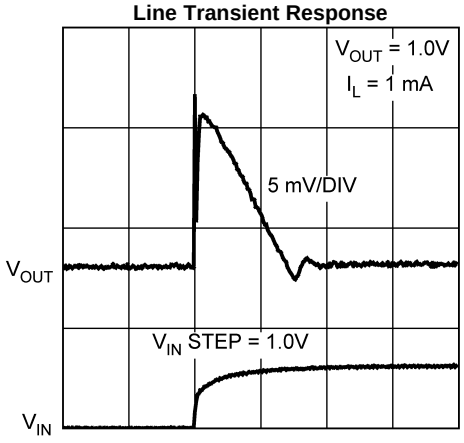


Figure 11.

Line Transient Response

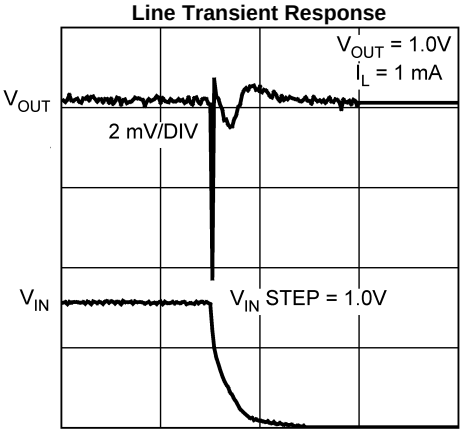


Figure 12.

Line Transient Response

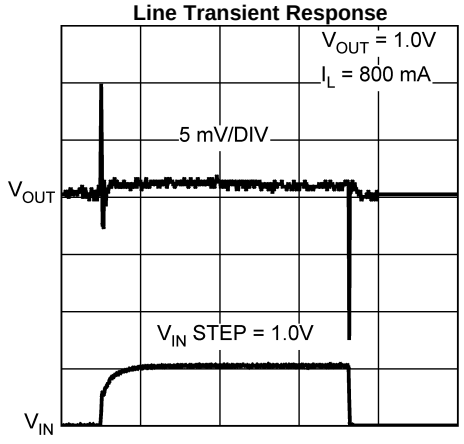


Figure 13.

Line Transient Response

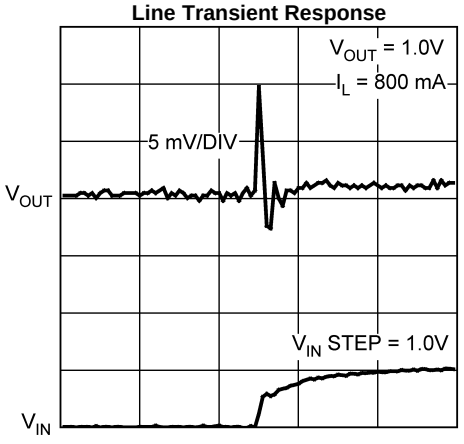


Figure 14.

Typical Performance Characteristics (continued)

Unless otherwise specified: V_{IN} = 3.3V, V_{OUT} = 1V, I_L = 1 mA, C_{IN} = 4.7 µF, C_{OUT} = 10 µF, $V_{S/D}$ = 2V, C_{BYP} = 10 nF, T_J = 25°C.

Line Transient Response

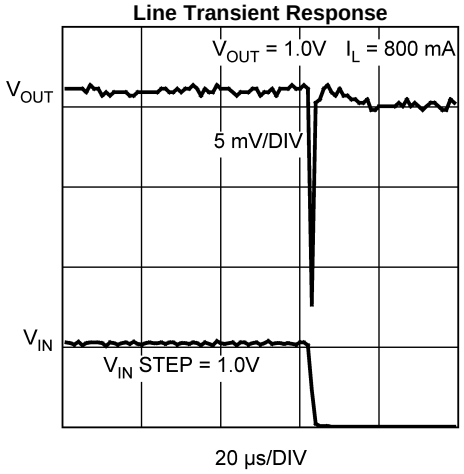


Figure 15.

Load Transient Response

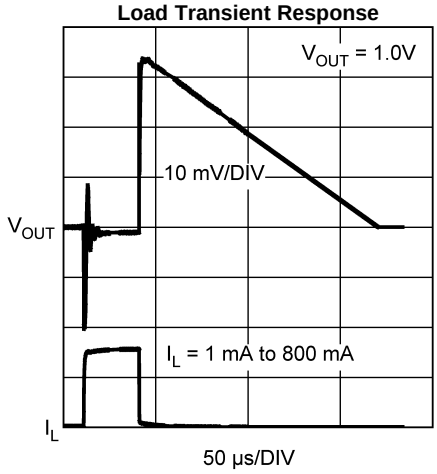


Figure 16.

Load Transient Response

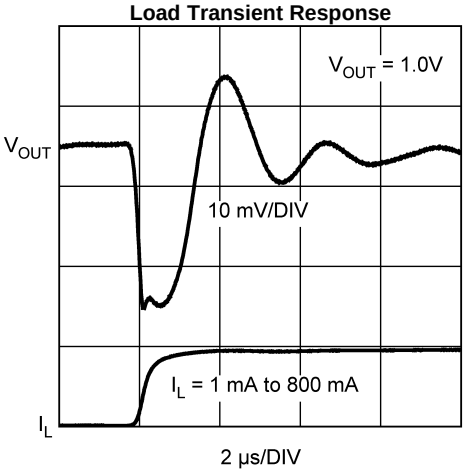


Figure 17.

Turn-On Characteristics

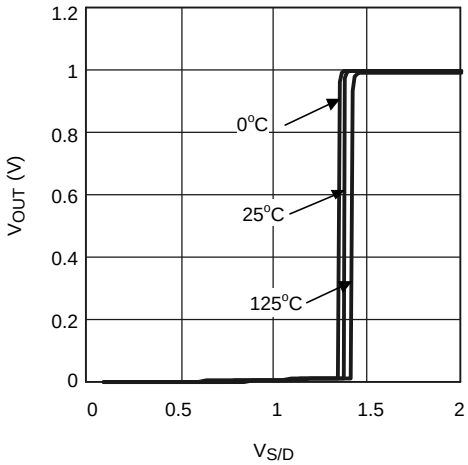
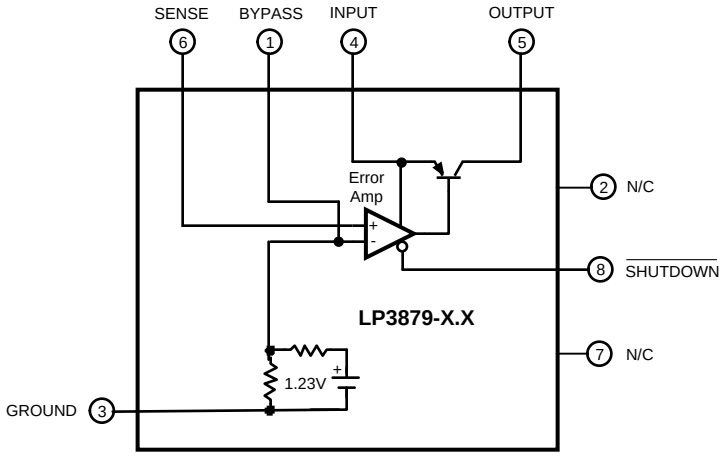


Figure 18.

Block Diagram



APPLICATION INFORMATION

PACKAGE INFORMATION

The LP3879 is offered in the 8-lead SO PowerPad or WSON surface mount packages to allow for increased power dissipation compared to the SO-8 and Mini SO-8.

EXTERNAL CAPACITORS

Like any low-dropout regulator, the LP3879 requires external capacitors for regulator stability. These capacitors must be correctly selected for good performance.

INPUT CAPACITOR: A capacitor whose value is at least 4.7 µF (±20%) is required between the LP3879 input and ground. A good quality X5R / X7R ceramic capacitor should be used.

Capacitor tolerance and temperature variation must be considered when selecting a capacitor (see Capacitor Characteristics section) to assure the minimum requirement of input capacitance is met over all operating conditions.

The input capacitor must be located not more than 0.5" from the input pin and returned to a clean analog ground. Any good quality ceramic or tantalum capacitor may be used, assuming the minimum input capacitance requirement is met.

OUTPUT CAPACITOR: The LP3879 requires a ceramic output capacitor whose size is at least 10 µF (±20%). A good quality X5R / X7R ceramic capacitor should be used. Capacitance tolerance and temperature characteristics must be considered when selecting an output capacitor.

The LP3879 is designed specifically to work with ceramic output capacitors, utilizing circuitry which allows the regulator to be stable across the entire range of output current with an ultra low ESR output capacitor.

The output capacitor selected must meet the requirement for minimum amount of capacitance and also have an ESR (equivalent series resistance) value which is within the stable range. A curve is provided which shows the stable ESR range as a function of load current (see Figure 19).

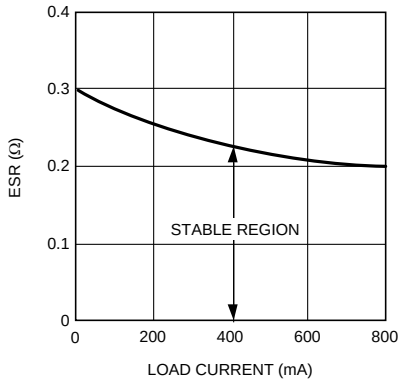


Figure 19. Stable Region For Output Capacitor ESR

Important: The output capacitor must maintain its ESR within the stable region *over the full operating temperature range of the application* to assure stability.

The output capacitor ESR forms a zero which is required to add phase lead near the loop gain crossover frequency, typically in the range of 50kHz to 200 kHz. The ESR at lower frequencies is of no importance. Some capacitor manufacturers list ESR at low frequencies only, and some give a formula for Dissipation Factor which can be used to calculate a value for a term referred to as ESR. However, since the DF formula is usually at a much lower frequency than the range listed above, it will give an unrealistically high value. If good quality X5R or X7R ceramic capacitors are used, the actual ESR in the 50 kHz to 200 kHz range will not exceed 25 milli Ohms. If these are used as output capacitors for the LP3879, the regulator stability requirements are satisfied.

It is important to remember that capacitor tolerance and variation with temperature must be taken into consideration when selecting an output capacitor so that the minimum required amount of output capacitance is provided over the full operating temperature range. (See Capacitor Characteristics section).

The output capacitor must be located not more than 0.5" from the output pin and returned to a clean analog ground.

NOISE BYPASS CAPACITOR: The 10 nF capacitor on the Bypass pin significantly reduces noise on the regulator output and is required for loop stability. However, the capacitor is connected directly to a high-impedance circuit in the bandgap reference.

Because this circuit has only a few microamperes flowing in it, any significant loading on this node will cause a change in the regulated output voltage. For this reason, DC leakage current through the noise bypass capacitor must never exceed 100 nA, and should be kept as low as possible for best output voltage accuracy.

The types of capacitors best suited for the noise bypass capacitor are ceramic and film. High-quality ceramic capacitors with either NPO or COG dielectric typically have very low leakage. 10 nF polypropolene and polycarbonate film capacitors are available in small surface-mount packages and typically have extremely low leakage current.

CAPACITOR CHARACTERISTICS

CERAMIC: The LP3879 was designed to work with ceramic capacitors on the output to take advantage of the benefits they offer: for capacitance values in the 10 µF range, ceramics are the least expensive and also have the lowest ESR values (which makes them best for eliminating high-frequency noise). The ESR of a typical 10 µF ceramic capacitor is in the range of 5 mΩ to 10 mΩ, which meets the ESR limits required for stability by the LP3879.

One disadvantage of ceramic capacitors is that their capacitance can vary with temperature. Many large value ceramic capacitors (≥ 2.2 µF) are manufactured with the Z5U or Y5V temperature characteristic, which results in the capacitance dropping by more than 50% as the temperature goes from 25°C to 85°C.

Another significant problem with Z5U and Y5V dielectric devices is that the capacitance drops severely with applied voltage. A typical Z5U or Y5V capacitor can lose 60% of its rated capacitance with half of the rated voltage applied to it.

For these reasons, X7R and X5R type ceramic capacitors must be used on the input and output of the LP3879.

SHUTDOWN INPUT OPERATION

The LP3879 is shut off by pulling the Shutdown input low, and turned on by pulling it high. If this feature is not to be used, the Shutdown input should be tied to V_{IN} to keep the regulator output on at all times.

To assure proper operation, the signal source used to drive the Shutdown input must be able to swing above and below the specified turn-on/turn-off voltage thresholds listed in the Electrical Characteristics section under $V_{ON/OFF}$.

REVERSE INPUT-OUTPUT VOLTAGE

The PNP power transistor used as the pass element in the LP3879 has an inherent diode connected between the regulator output and input.

During normal operation (where the input voltage is higher than the output) this diode is reverse-biased.

However, if the output is pulled above the input, this diode will turn ON and current will flow into the regulator output.

In such cases, a parasitic SCR can latch which will allow a high current to flow into V_{IN} (and out the ground pin), which can damage the part.

In any application where the output may be pulled above the input, an external Schottky diode must be connected from V_{IN} to V_{OUT} (cathode on V_{IN}, anode on V_{OUT}), to limit the reverse voltage across the LP3879 to 0.3V (see Absolute Maximum Ratings).

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LP3879MR-1.0	ACTIVE	SO PowerPAD	DDA	8	95	TBD	Call TI	Call TI		3879 MR1.0	Samples
LP3879MR-1.0/NOPB	ACTIVE	SO PowerPAD	DDA	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		3879 MR1.0	Samples
LP3879MR-1.2	ACTIVE	SO PowerPAD	DDA	8	95	TBD	Call TI	Call TI		LP3879 MR1.2	Samples
LP3879MR-1.2/NOPB	ACTIVE	SO PowerPAD	DDA	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		LP3879 MR1.2	Samples
LP3879MRX-1.0	ACTIVE	SO PowerPAD	DDA	8	2500	TBD	Call TI	Call TI		3879 MR1.0	Samples
LP3879MRX-1.0/NOPB	ACTIVE	SO PowerPAD	DDA	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		3879 MR1.0	Samples
LP3879MRX-1.2	ACTIVE	SO PowerPAD	DDA	8	2500	TBD	Call TI	Call TI		LP3879 MR1.2	Samples
LP3879MRX-1.2/NOPB	ACTIVE	SO PowerPAD	DDA	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		LP3879 MR1.2	Samples
LP3879SD-1.0	ACTIVE	WSON	NGT	8	1000	TBD	Call TI	Call TI		79SD1.0	Samples
LP3879SD-1.0/NOPB	ACTIVE	WSON	NGT	8	1000	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM		79SD1.0	Samples
LP3879SD-1.2	ACTIVE	WSON	NGT	8	1000	TBD	Call TI	Call TI		79SD1.2	Samples
LP3879SD-1.2/NOPB	ACTIVE	WSON	NGT	8	1000	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM		79SD1.2	Samples
LP3879SDX-1.0	ACTIVE	WSON	NGT	8	4500	TBD	Call TI	Call TI		79SD1.0	Samples
LP3879SDX-1.0/NOPB	ACTIVE	WSON	NGT	8	4500	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM		79SD1.0	Samples
LP3879SDX-1.2	ACTIVE	WSON	NGT	8	4500	TBD	Call TI	Call TI		79SD1.2	Samples
LP3879SDX-1.2/NOPB	ACTIVE	WSON	NGT	8	4500	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM		79SD1.2	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

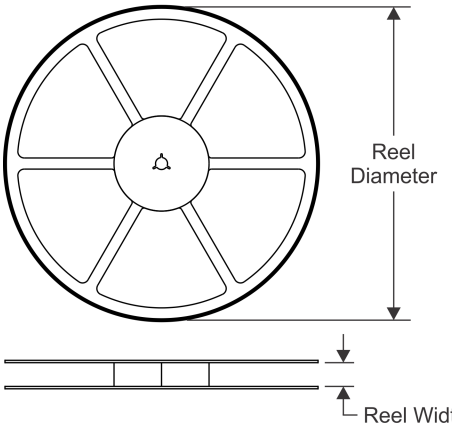
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

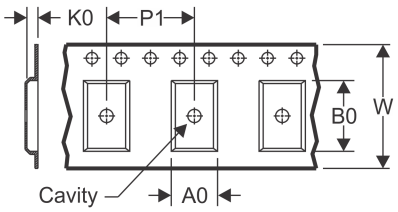
(4) Only one of markings shown within the brackets will appear on the physical device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

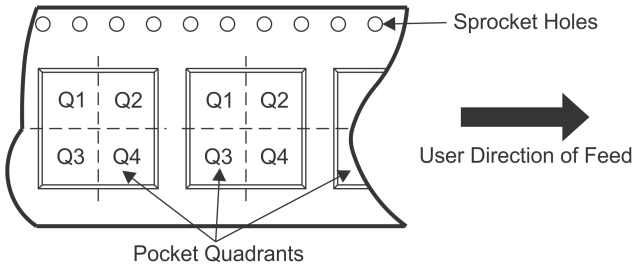


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

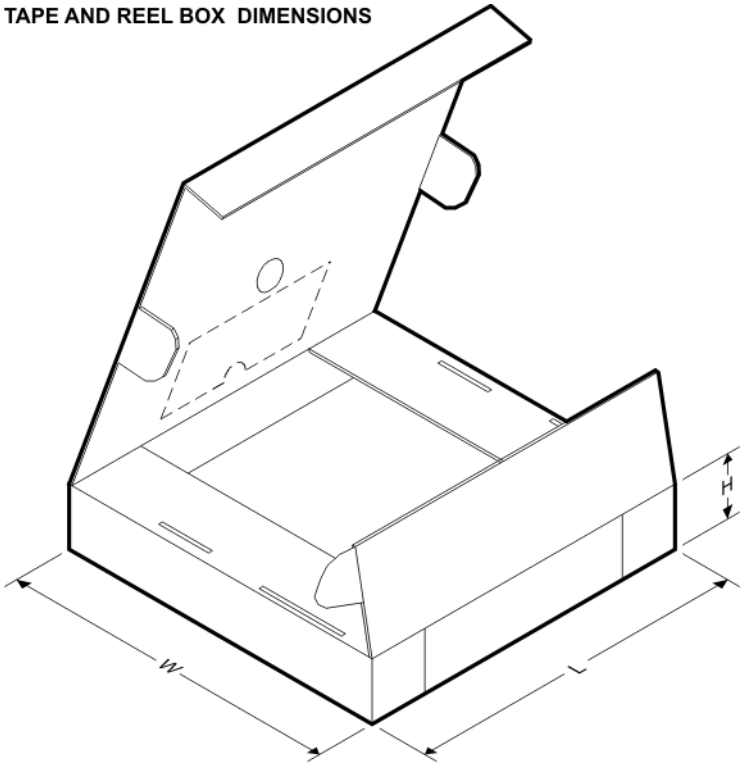
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP3879MRX-1.0	SO Power PAD	DDA	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LP3879MRX-1.0/NOPB	SO Power PAD	DDA	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LP3879MRX-1.2	SO Power PAD	DDA	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LP3879MRX-1.2/NOPB	SO Power PAD	DDA	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LP3879SD-1.0	WSON	NGT	8	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3879SD-1.0/NOPB	WSON	NGT	8	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3879SD-1.2	WSON	NGT	8	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3879SD-1.2/NOPB	WSON	NGT	8	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3879SDX-1.0	WSON	NGT	8	4500	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3879SDX-1.0/NOPB	WSON	NGT	8	4500	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3879SDX-1.2	WSON	NGT	8	4500	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3879SDX-1.2/NOPB	WSON	NGT	8	4500	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1

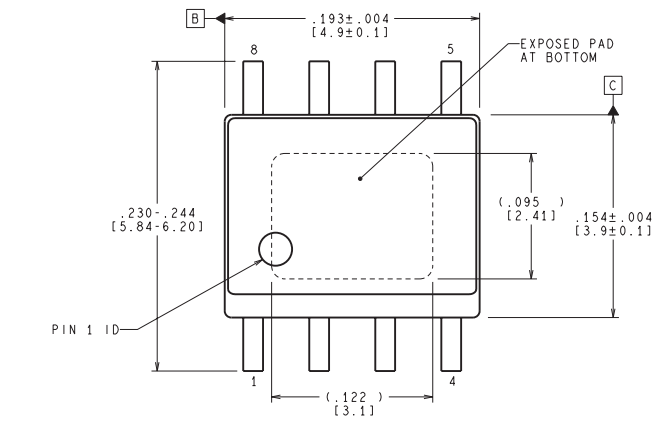
TAPE AND REEL BOX DIMENSIONS

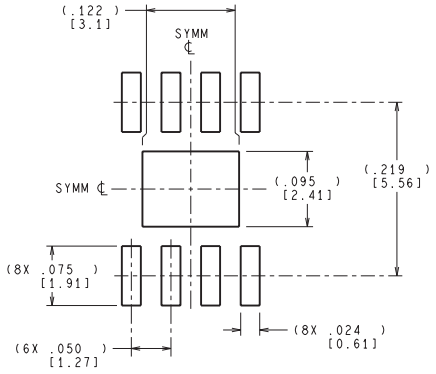


*All dimensions are nominal

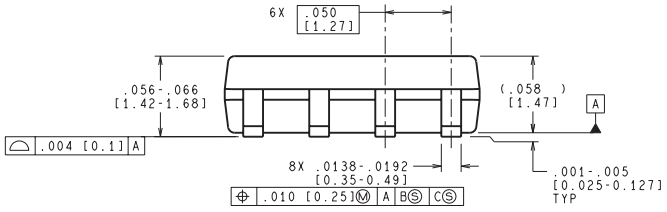
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP3879MRX-1.0	SO PowerPAD	DDA	8	2500	358.0	343.0	63.0
LP3879MRX-1.0/NOPB	SO PowerPAD	DDA	8	2500	358.0	343.0	63.0
LP3879MRX-1.2	SO PowerPAD	DDA	8	2500	358.0	343.0	63.0
LP3879MRX-1.2/NOPB	SO PowerPAD	DDA	8	2500	358.0	343.0	63.0
LP3879SD-1.0	WSON	NGT	8	1000	203.0	190.0	41.0
LP3879SD-1.0/NOPB	WSON	NGT	8	1000	203.0	190.0	41.0
LP3879SD-1.2	WSON	NGT	8	1000	203.0	190.0	41.0
LP3879SD-1.2/NOPB	WSON	NGT	8	1000	203.0	190.0	41.0
LP3879SDX-1.0	WSON	NGT	8	4500	349.0	337.0	45.0
LP3879SDX-1.0/NOPB	WSON	NGT	8	4500	349.0	337.0	45.0
LP3879SDX-1.2	WSON	NGT	8	4500	349.0	337.0	45.0
LP3879SDX-1.2/NOPB	WSON	NGT	8	4500	349.0	337.0	45.0

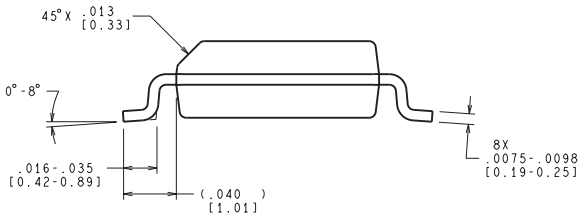
DDA0008B





RECOMMENDED LAND PATTERN





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MRA08B (Rev B)

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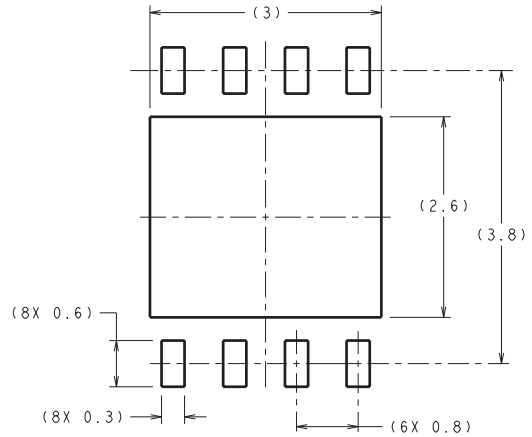

DIMENSIONS ARE IN MILLIMETERS
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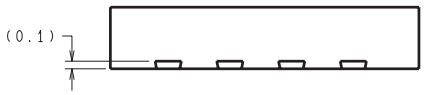
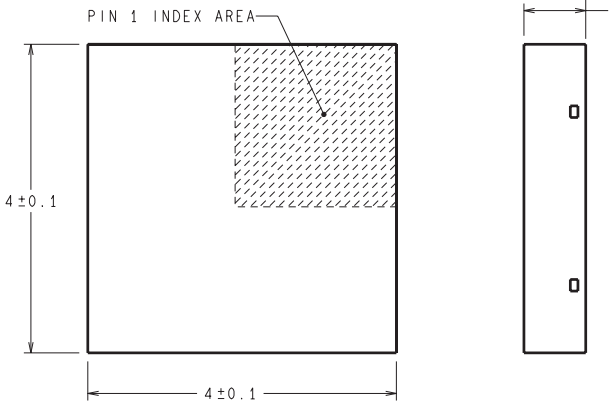
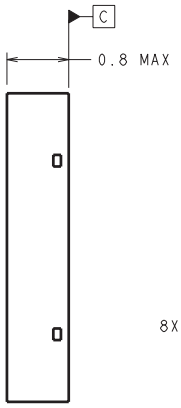
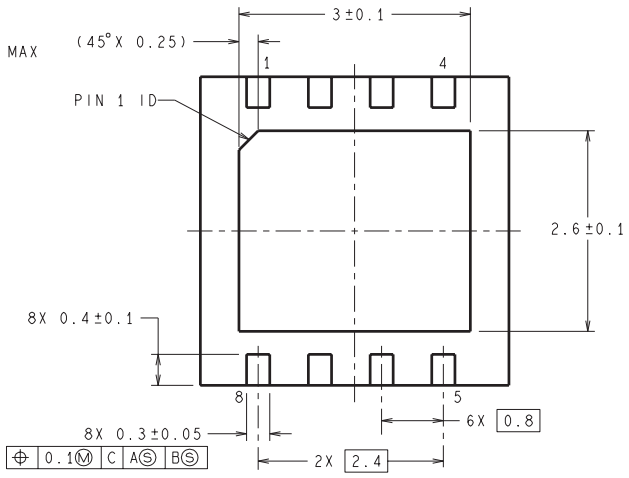


RECOMMENDED LAND PATTERN







SDC08A (Rev A)

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